

The paragraph beginning on page 12, line 16 is amended as follows:

Although specific embodiments have been illustrated and described herein, it will be appreciated by those of ordinary skill in the art that any arrangement that is calculated to achieve the same purpose may be substituted for the specific embodiment shown. This application is intended to cover any adaptations or variations of the present subject matter [invention]. Therefore, it is manifestly intended that embodiments of this invention be limited only by the claims and the equivalents thereof.

IN THE CLAIMS

Please substitute the claim set in the appendix entitled "Clean Version of Pending Claims" for the previously pending claim set. The substitute claim set is intended to reflect amendment of previously pending claim 21. The specific amendment to claim 21 is detailed as follows:

21. (Twice Amended) An electronic system comprising an electronic assembly having at least one integrated circuit package comprising:

- a substrate;
- a die positioned on a surface of the substrate, the die having a back surface;
- an adhesion layer formed on the back surface;
- a solder-wettable layer formed on the adhesion layer;
- a lid positioned over the die; and
- a solderable thermally conductive element coupling the solder-wettable layer and the lid.

REMARKS

Applicants have carefully reviewed and considered the Office Action mailed on September 16, 2002, and the references cited therewith.